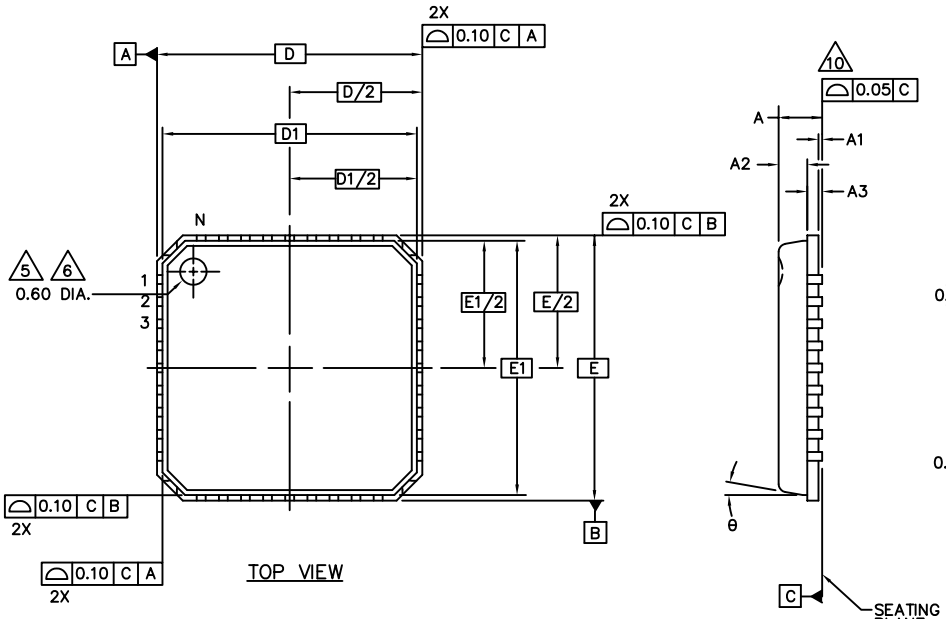
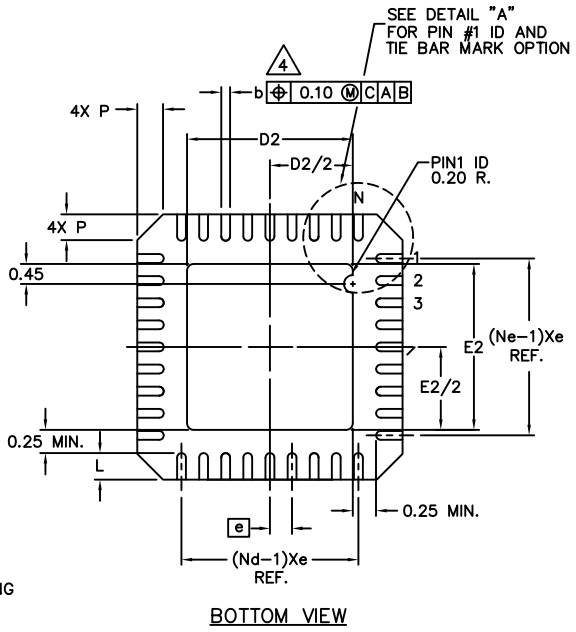
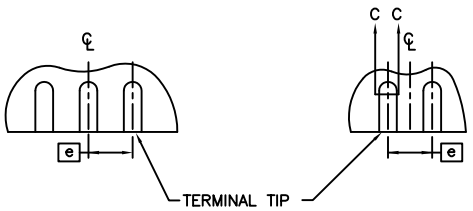
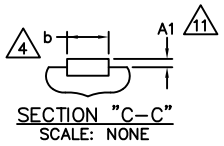
HIGH DENSITY LEADFRAME

REVISION HISTORY				
REV	DESCRIPTION	DATE	DRAWN BY	RELEASED
02	INC. PER DCN #A48675.	06/07 2000	SSJ	SSJ
03	INC. PER DCN #A48854.	08/15 2000	SSJ	SSJ
04	INC. PER DCN #A50588.	02/16 2001	SSJ	SSJ
05	INC. PER DCN #A53183.	11/09 2001	HIJ	HIJ
06	ADDED EXPOSED PAD SIZE PER DCN #C19398.	10/20 2005	HIJ	HIJ









THIRD ANGLE PROJECTION

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

APPROVALS	DATE
DRAWN HI JEON	05/28 2001
CHECKED SS JANG	05/28 2001
APPROVED SS JANG	05/28 2001
RELEASED JD KIM	10/20 2005

TITLE: PACKAGE OUTLINE, MLF2, 6 X 6 mm BODY

SIZE: A3 | DWG NUMBER: 45278 | REV: 06

SCALE: NONE | CUSTOMER CODE: XXXX | SHEET 1 OF 5

FORM NO. MDFORM3J.DWG